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# United States Patent [19]

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[54] COATING APPARATUS AND METHOD FOR APPLYING A LIQUID TO A SEMICONDUCTOR WAFER INCLUDING SELECTING A NOZZLE ON A STAND BY STATE

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[58] Field of Search ..... 427/426, 422, 425;  
118/302, 313, 321, 411, 600, 52

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### [57] ABSTRACT

Disclosed is a coating apparatus for applying a resist or developing solution to a semiconductor wafer. This coating apparatus comprises a plurality of nozzles supplied with various resist from a resist source and each adapted to drip the different solution onto the wafer, a vessel in which the nozzles is kept on stand-by, while maintaining the liquids in a predetermined state in the vicinity of discharge port portions of the nozzles, when the nozzles need not be operated, and a nozzle operating mechanism for selecting one of the nozzles kept on stand-by in the vessel, and transporting the selected nozzle to the location of the wafer, whereby the resist is applied to the wafer by means of only the nozzle transported by the nozzle operating mechanism.

6 Claims, 8 Drawing Sheets

